IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard  Form Type http://www.ipc.org/IPC-175x  Form Type Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				aterials and	ials and Mfg Information					
Supplier Inforn	nation														
Company name*			Company unique ID			Ī	Unique ID Authority				Respo	Response Date*			
onsemi										2025-	2025-06-03				
Contact Name			Title - Contact			1	Phone - Contact*				Emai	Email - Contact*			
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			]	Phone - Representative*				Emai	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
Requesto	Requester Item Number Mfr I		Item Number Mfr Item Name				Effective Dat	te Versi	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		NRVUS1	IFFA	HER SOD123FA	GPPN 1A 300	)V	2025-06-03			TSCBE		18.79156	mg	Each	
	Process Information				GED 000 150								AD 9		
8		•		-STD-020 MS	SL Rating		ocess Body Temperature   Max Time at Peak		1		er of Reflow Cyo	eles			
<u> </u>	n (Sn) - annealed	C	CU Alloy	1			260		C	30	sec	conds 3			
omments															
	time at peak temperature														
or more informati	on regarding material co	mposition <b>j</b>	please refer t	o page 3											

<b>RoHS Material Composition Declaration</b>			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Iiability and the Company's remedies for issues that arise regarding information the Supplier prov											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).  Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.72998	mg	Supplier	Silicon (Si)	7440-21-3		0.657	mg
			В	Nickel (Ni)	7440-02-0		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0011	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0672	mg
Die Attach Solder	4.11996	mg	Supplier	Silver (Ag)	7440-22-4		0.103	mg
			A	Lead (Pb)	7439-92-1	7a	3.811	mg
			Supplier	Tin (Sn)	7440-31-5		0.206	mg
Lead Frame	6.79991	mg	Supplier	Iron (Fe)	7439-89-6		0.0068	mg
			Supplier	Copper (Cu)	7440-50-8		6.7911	mg
			Supplier	Phosphorus (P)	7723-14-0		0.002	mg
Mold Compound-Black	6.94164		Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.0725	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0715	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.715	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5.0826	mg
Plating	0.20007	mg	Supplier	Tin (Sn)	7440-31-5		0.2001	mg